Specification of Thermoelectric Module

TES1-12740P

Description

The 127 couples, 31 mm x 31/34 mm size module is a single stage module which is made of our high performance ingot to achieve superior cooling performance and 70°C or larger delta Tmax, is designed for superior cooling and heating applications. Beyond the standard below, we can design and manufacture the custom made module according to your special requirements.

Features

- No moving parts, no noise, and solid-state
- Compact structure, small in size, light in weight
- Environmental friendly
- RoHS compliant
- Precise temperature control
- Exceptionally reliable in quality, high performance

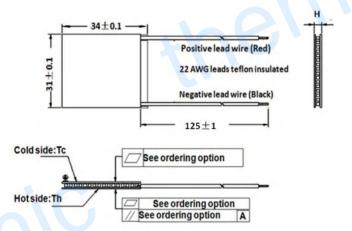
Application

- Food and beverage service refrigerator
- Portable cooler box for cars
- Liquid cooling
- Temperature stabilizer
- CPU cooler and scientific instrument
- Photonic and medical systems

Performance Specification Sheet

Th (°C)	27	50	Hot side temperature at environment: dry air, N ₂	
DT _{max} (°C)	70	79	Temperature Difference between cold and hot side of the module when cooling capacity is zero at cold side	
U _{max} (Voltage)	15.9	17.2	Voltage applied to the module at DT _{max}	
I _{max} (Amps)	4	4	DC current through the modules at DT _{max}	
Q _{Cmax} (Watts)	40.3	43.4	Cooling capacity at cold side of the module under DT=0 °C	
AC resistance (Ohms)	3.0	3.3	The module resistance is tested under AC	
Tolerance (%)	± 10		For thermal and electricity parameters	

Geometric Characteristics Dimensions in millimeters



Ordering Option

C	Thickness	Flatness/	Lead wire length(mm)
Suffix	H (mm)	Parallelism (mm)	Standard/Optional length
TF	$0:3.2\pm0.1$	0: 0.08/0.08	125±1/Specify
TF	$1: 3.2 \pm 0.03$	1: 0.03/0.03	125±1/Specify

Eg. TF01: Thickness 3.2 ± 0.1 (mm) and Flatness 0.03/0.03 (mm)

Manufacturing Options

A. Solder:

1. T100: BiSn (Tmelt=138°C)

1. NS: No sealing (Standard)

B. Sealant:

2. T200: CuAgSn (Tmelt = 217° C)

2. SS: Silicone sealant

3. T240: SbSn (Tmelt = 240° C)

3. EPS: Epoxy sealant

C. Ceramics:

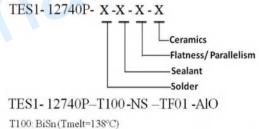
1. Alumina (Al₂O₃, white 96%)

D. Ceramics Surface Options: 1. Blank ceramics (not metalized)

2. Aluminum Nitride (AlN)

2. Metalized

Naming for the Module

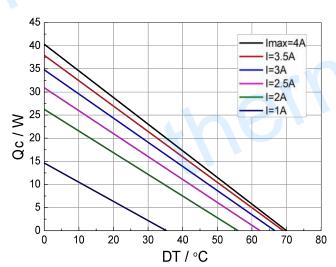


NS: No sealing AlO: Alumina, white 96%

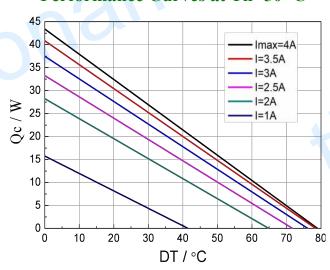
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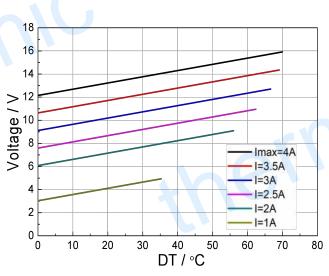


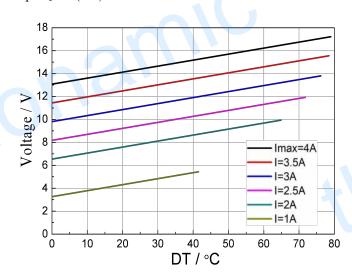


Performance Curves at Th=50 °C

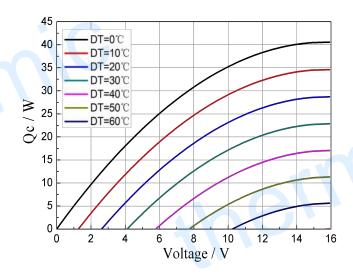


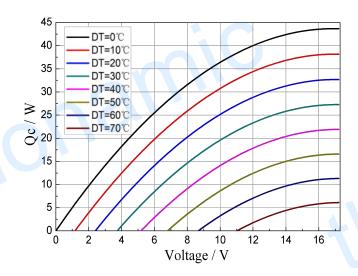
Standard Performance Graph Qc= f(DT)





Standard Performance Graph V= f(DT)





Standard Performance Graph Qc = f(V)

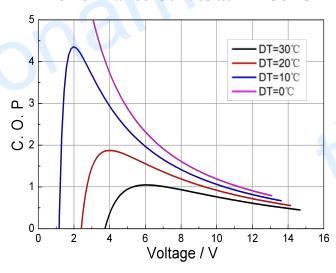
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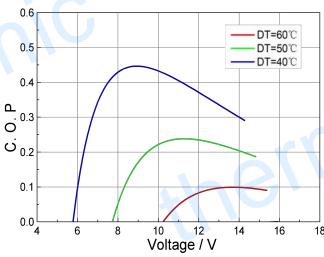
Performance Curves at Th=27 °C

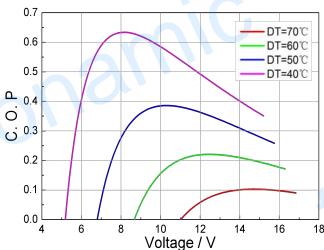
DT=30°C DT=20°C DT=10°C DT=0°C DT=0°C Voltage / V

Performance Curves at Th=50 °C



Standard Performance Graph COP = f(V) of DT ranged from 0 to 30 °C





Standard Performance Graph COP = f(V) of DT ranged from 40 to 60/70 °C

Remark: The coefficient of performance (COP) is the cooling power Qc/Input power ($V \times I$).

Operation Caution

- Attach the cold side of module to the object to be cooled
- Attach the hot side of module to a heat radiator for heat dissipating
- Operation below I_{max} or V_{max}
- Work under DC

Note: All specifications subject to change without notice.